



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Hui et al.

**Serial No.:** 09/916,197

**Filed:** July 27, 2001

**For:** METHOD FOR ENCAPSULATING  
INTERMEDIATE CONDUCTIVE  
ELEMENTS CONNECTING A  
SEMICONDUCTOR DIE TO A  
SUBSTRATE AND SEMICONDUCTOR  
DEVICES SO PACKAGED

**Confirmation No.:** 7070

**Examiner:** J. Vigushin

**Group Art Unit:** 2827

**Attorney Docket No.:** 2269-4712US  
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**Person making Deposit:** Christopher Haughton

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Specification** appear on page 3 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 4 of this paper.

**Amendments to the Drawings** appear on page 23 of this paper and include both attached replacement sheets and annotated sheets showing changes.

**Remarks** begin on page 24 of this paper.

An **Appendix** including amended drawing figures is attached following page 24 of this paper.

IN THE DRAWINGS:

The attached sheets of drawings include changes to FIGS. 6, 7A, 8A and 8B. These sheets, which include FIGS. 5-6, 7-7B, and 8A-8C, replace the original sheets including FIGS. 5-6, 7-7B and 8A-8C.

FIGS. 6, 7A, 8A and 8B have been amended herein. Specifically, FIG. 6 has been revised to add the reference numeral --1-- with appropriate lead line arrow; FIG. 7A has been revised to change the reference numeral "38" to --38'-- to eliminate redundancy with previously used reference numerals; and FIGS. 8A and 8B have been revised to delete the reference numeral "37'" and their corresponding lead line. No new matter has been added.